

REMARKS/ARGUMENTS

The foregoing amendment seeks to replace Table 2 with a corrected version showing the correct number of examples; namely, 11 and the correct name for γ -glycidoxypropyl-trimethoxysilane. A copy of the Table 2 as amended on Feb. 6, 2006, is attached showing the strike through of the incorrect spelling of γ -glycidoxypropyl-trimethoxysilane.

The amendment of October 30, 2006, contained the incorrect number of examples and failed to take into account that Table 2 had been corrected previously in the amendment of February 6, 2006 to show the correct number of examples as 11 instead of 15.

Correction of the record is therefore respectfully requested.

Respectfully submitted,

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TABLE 2

	Comparative Example										
	1	2	3	4	5	6	7	8	9	10	11
Phenol biphenyl/alkyl type epoxy resin	7.4	9.4		7.4	7.5	7.6	7.35	7.35	7.4	7.35	7.35
Biphenyl type epoxy resin											
Cresol novolac type epoxy resin			6.9								
Phenol biphenyl/alkyl resin	5.5			5.5	5.52	5.65	5.5	5.5	5.5	5.5	5.5
Phenol/alkyl resin			6.0								
Phenol novolac resin		3.5									
Spherical fused silica	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidyloxypropyltrimethoxysilane	0.4	0.4	0.4		0.4		0.4	0.4	0.4	0.4	0.4
7-Me rcapto pro pytrimethoxysilane				0.4							
Triphenylphosphine	0.2	0.15	0.15	0.2	0.06	0.2	0.2	0.2			
DBU									0.2		
Curing accelerator of formula C7)										0.25	
Curing accelerator of formula C8)											0.25
2,3-Dihydroxynaphthalene		0.05	0.05			0.05					
1,2-Dihydroxynaphthalene											
Catechol											
Pyrogallol											
1,6-Dihydroxynaphthalene							0.05				
Resorcinol								0.05			
Caruba wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	76	71	62	114	76	78	81	68	89	77
Curing torque ratio (%)	65	67	70	62	7	56	65	64	57	85	89
Solder resistance-cracking	4	2	chip exposure	3		9	5	4	4	2	3
Chip delamination	0	10	HB	0	Poor	0	0	0	0	0	0
Internal crack	V-0	V-1		V-0	Releasing	V-0	V-0	V-0	V-0	V-0	V-0
Fire retardancy											